



## 1-LineLow Capacitance Bi-directional TVS Diode

### General description

GBLC05C a 5.0V bi-directional TVS diode, utilizing leading monolithic silicon technology to provide fast response time and low ESD clamping voltage, making his device an ideal solution for protecting voltage sensitive high-speed data lines. The GBLC05C has a low capacitance with a typical value at 0.6pF, and complies with the IEC61000-4-2(ESD) standard with ±30KV air and ±30KV contact discharge. It is assembled into a leadfree SOD-323 package. The small size, low capacitance and high ESD surge protection make GBLC05C an idea choice to protect cell phone, wireless systems, and communication equipment.

### Features and benefits

- Ultra Low Capacitance 0.6 pF(Typ)
- 350W peak pulse power (8/20μS)
- Working Voltage 5.0V
- Low leakage current: nA Level
- Complies with following standards:
  - IEC 61000-4-2 (ESD) immunity test  
Air discharge: ±30kV / Contact discharge: ±30kV
  - IEC61000-4-5 (Lightning) 18A (8/20μS)
  - IEC61000-4-4 (EFT) 80A (5/50nS)
- RoHS compliant

### Application information

- High- speed data lines
- Smart phones
- USB Ports
- Wireless Systems
- Ethernet 10/100/1000 Base T

### Ordering information

Device	Marking	Packaging	Reel Size
GBLC05C	AC	3000/Tape & Reel	7 inch

### Schematic & Pin configuration

Simplified outline	Graphic symbol
	

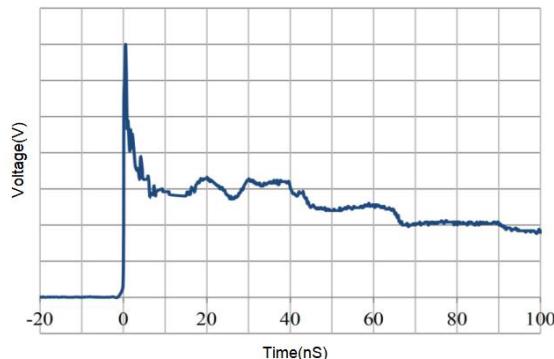
### Maximum Ratings ( $T_A = 25^\circ\text{C}$ , unless otherwise specified)

Parameter	Symbol	Value	Unit
Peak Pulse Power ( $tp = 8/20\mu\text{s}$ )	$P_{PK}$	350	W
Peak Pulse Current ( $tp = 8/20\mu\text{s}$ )	$I_{PP}$	18	A
ESD voltage IEC 61000-4-2 (air discharge)	$V_{ESD}$	30	KV
ESD voltage IEC 61000-4-2 (contact discharge)	$V_{ESD}$	30	KV
Storage Temperature Range	$T_{STG}$	-55 to +150	$^\circ\text{C}$
Operating Temperature Range	$T_{OP}$	-40 to +125	$^\circ\text{C}$

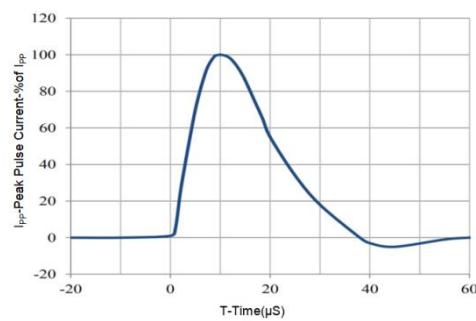
### Electrical Characteristics ( $T_A = 25^\circ\text{C}$ , unless otherwise specified)

Parameter	Symbol	Min	Typ	Max	Unit	Condition
Reverse Working Voltage	$V_{RWM}$	--	--	5.0	V	
Breakdown Voltage	$V_{BR}$	6.1	6.8	8.0	V	$I_T=1\text{mA}$
Leakage Current $I_{LEAK}$	$I_R$	--	--	200	nA	$V_{RWM}=5.0\text{V}$
Clamping Voltage	$V_C$	--	8.0	10.0	V	$I_{PP}=1\text{A}, T_p=8/20\mu\text{s}$
Clamping Voltage	$V_C$	--	16.0	20.0	V	$I_{PP}=18\text{A}, T_p=8/20\mu\text{s}$
Junction Capacitance	$C_J$	--	0.6	0.9	pF	$V_R=0\text{V}, f=1\text{MHz}$

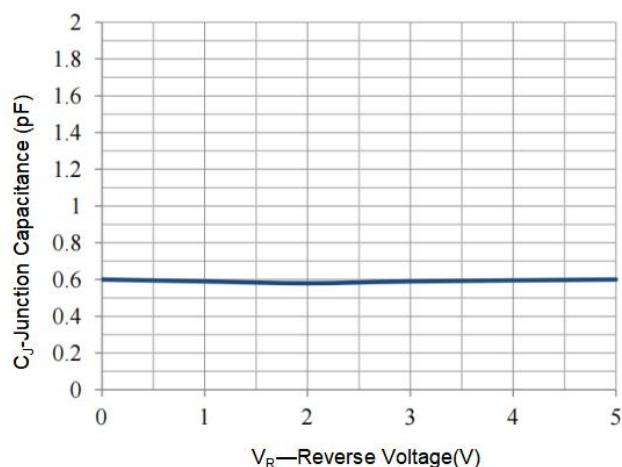
### Typical Performance Characteristics ( $T_A=25^\circ\text{C}$ unless otherwise Specified)



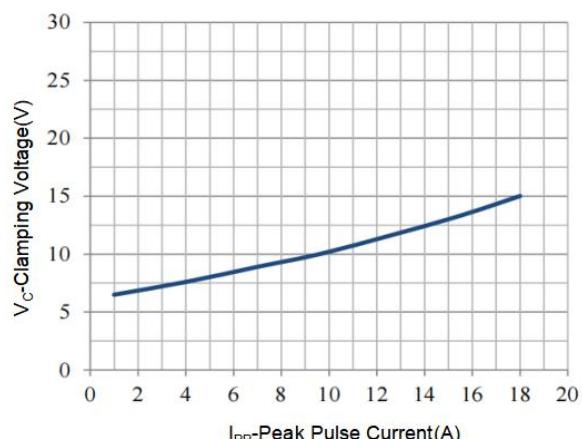
IEC61000-4-2 Pulse Waveform



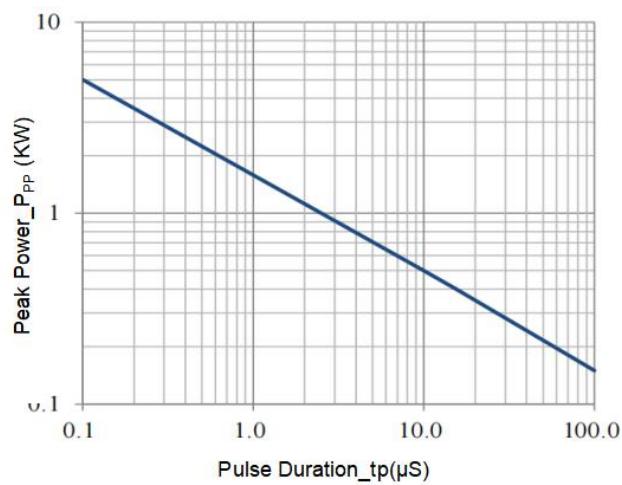
IEC61000-4-5 8X20μs Pulse Waveform



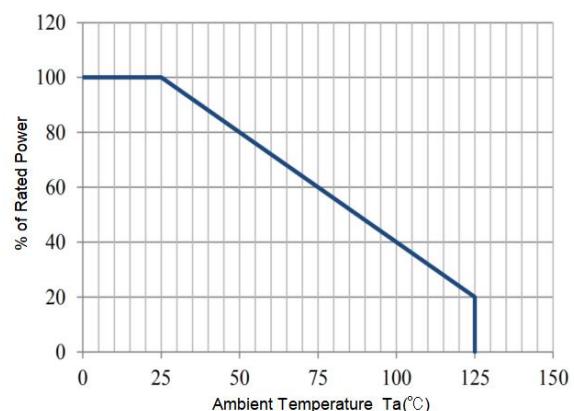
Junction Capacitance vs. Reverse Voltage



Clamping Voltage vs. Peak Pulse Current



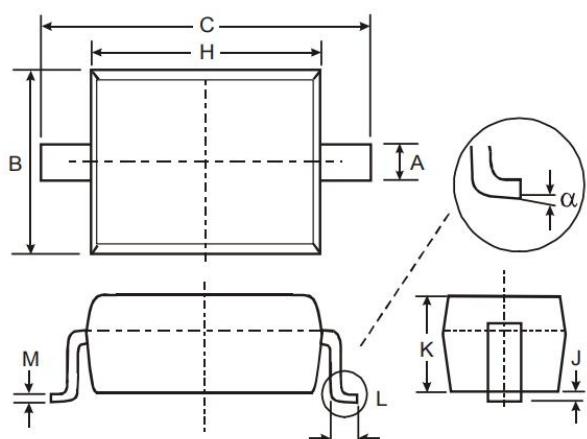
Peak Pulse Power vs. Pulse Time



Power Derating Curve

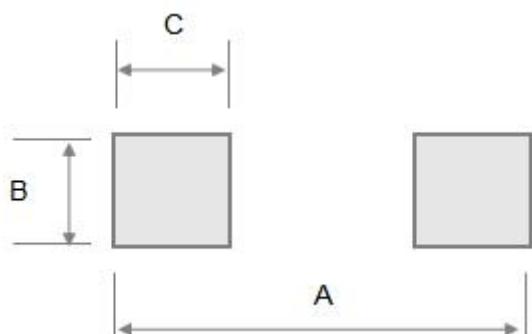
### Package Outline Dimensions (mm)

SOD323



SYMBOL	DIMENSIONS	
	MIN	MAX
A	0.25	0.40
B	1.20	1.40
C	2.30	2.70
H	1.50	1.80
J	0.01	0.15
K	0.80	1.10
L	0.20	0.40
M	0.08	0.25
α	0°	8°

### Soldering Footprint (mm)



SYMBOL	DIMENSIONS
A	0.32
B	0.80
C	0.80